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# ACM SIGSOFT Distinguished Artifact Award ICSE 2019

**41<sup>st</sup> IEEE/ACM International Conference on  
Software Engineering**

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Montreal, Canada

*Presented to*

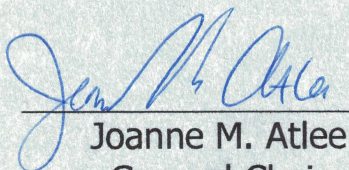
**Lili Wei**  
The Hong Kong  
University of  
Science and  
Technology

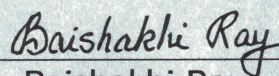
**Yepang Liu**  
Southern University  
of Science and  
Technology

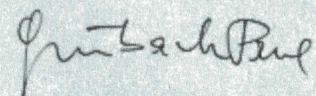
**Shing-Chi Cheung**  
The Hong Kong  
University of  
Science and  
Technology

*For*

**PIVOT: Learning API-Device Correlations to Facilitate  
Android Compatibility Issue Detection**

  
Joanne M. Atlee  
General Chair

  
Baishakhi Ray  
Artifact Evaluation Co-Chairs

  
Paul Grünbacher  
Artifact Evaluation Co-Chairs